

12V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
10)/	8mΩ @ V _{GS} = 4.5V	12.2A
12V	12.5mΩ @ V _{GS} = 2.5V	10.4A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Battery Management Application
- Power Management Functions
- DC-DC Converters

Features

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part.
 A listing can be found at

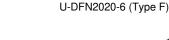
https://www.diodes.com/products/automotive/automotive-products/.

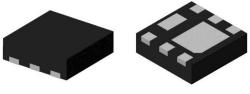
 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

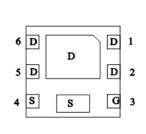
Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (Approximate)

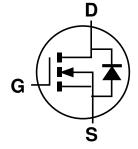




Top View Bottom View



Pin Out Bottom View



Internal Schematic

Ordering Information (Note 4)

Part Number	Reel Size (inches)	Case	Quantity per Reel
DMN1008UFDF-7	7	U-DFN2020-6 (Type F)	3,000
DMN1008UFDF-13	13	U-DFN2020-6 (Type F)	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



8N = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Date Code Ney												
Year	2015		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	С		Н	I	J	K	L	М	N	0	Р	R
		l I	l I	l I	I		l I	l I	l I	l I		l.
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



8N = Product Type Marking Code YWX = Date Code Marking

Y = Year (ex: 0 = 2020)
W = Week (ex: a = Week 27; z Represents Week 52 and 53)
X = Internal Code (ex: U = Monday)

Date Code Key

Year	2015	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	5	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Υ	Z



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	12	V		
Gate-Source Voltage			V_{GSS}	±8	V
Continuous Drain Current, V _{GS} = 4.5V (Note 6)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	12.2 9.8	А
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%	o)		I _{DM}	60	Α
Continuous Source-Drain Diode Current (Note 6)	T _A = +25°C	Is	1.8	Α	
Avalanche Current, L = 0.1mH (Note 7)	I _{AS}	16.4	Α		
Avalanche Energy, L = 0.1mH (Note 7)			E _{AS}	13.5	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Dawer Dissipation (Note 5)	T _A = +25°C	D	0.7	W
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	0.4	VV
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{0JA}	168	°C/W
Total Davier Dissipation (Note C)	T _A = +25°C	D	1.7	W
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	P_{D}	1.0	VV
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	74	°C/W
Thermal Resistance, Junction to Case (Note 6)	·	R _{eJC}	12	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

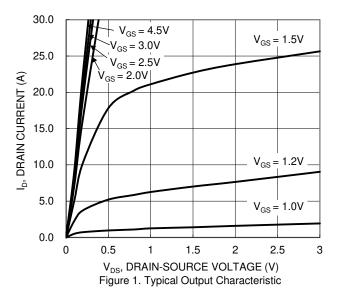
Electrical Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	12		_	٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 9.6V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.3	-	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			6.6	8		$V_{GS} = 4.5V, I_D = 5A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	7.6	11	mΩ	$V_{GS} = 3.0V, I_D = 5A$	
			8.5	12.5		$V_{GS} = 2.5V, I_D = 5A$	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	$V_{GS} = 0V$, $I_S = 5A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	995	_		24.14	
Output Capacitance	C _{oss}	_	305	_	pF	$V_{DS} = 6V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	270	_		I = 1.0IVII IZ	
Gate Resistance	R_g	_	1.5	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	13.6	_			
Total Gate Charge (V _{GS} = 8V)	Qg	_	23.4	_	nC	V _{DS} = 6V. I _D = 5A	
Gate-Source Charge	Q _{gs}	_	1.3	_	110	V _{DS} = 6v, I _D = 5A	
Gate-Drain Charge	Q_{gd}	_	3.3	_			
Turn-On Delay Time	t _{D(ON)}	_	3.5	_			
Turn-On Rise Time	t _R	_	6.6	_	ns	$V_{DS} = 6V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	17.5	_	115	$R_G = 2\Omega$, $I_D = 5A$	
Turn-Off Fall Time	t _F	_	7.5	_			
Reverse Recovery Time	t _{RR}	_	15	_	ns	I _F = 5A, di/dt = 200A/μs	
Reverse Recovery Charge	Q _{RR}	_	4	_	nC	I _F = 5A, di/dt = 200A/μs	

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.







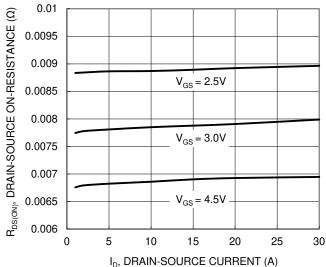


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

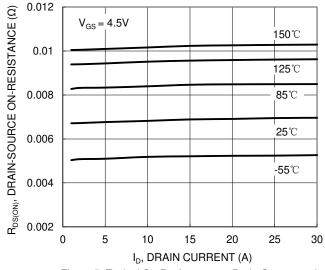
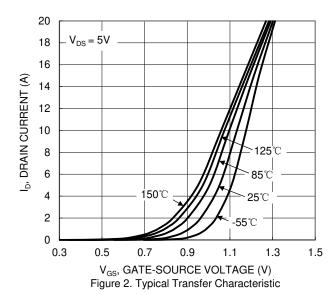


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



0.08 O.08 O.04 O.004 O.002 O.0

 V_{GS} , GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic

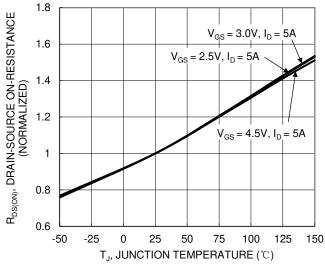


Figure 6. On-Resistance Variation with Junction Temperature





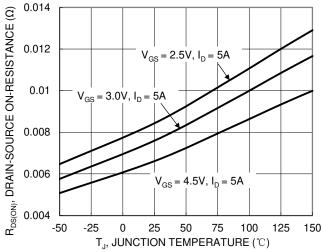


Figure 7. On-Resistance Variation with Junction Temperature

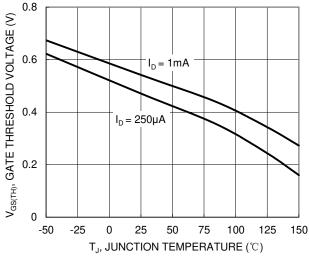
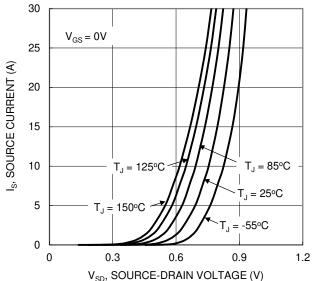
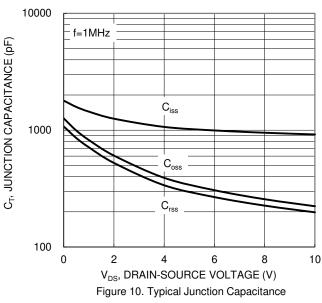


Figure 8. Gate Threshold Variation vs. Junction Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current



400

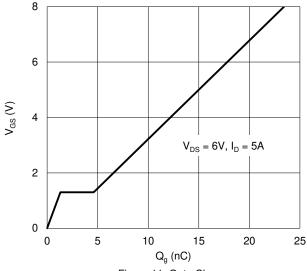


Figure 11. Gate Charge

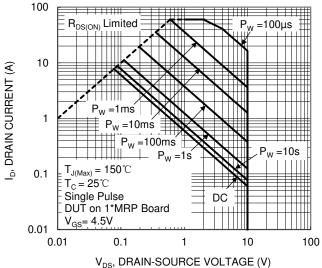


Figure 12. SOA, Safe Operation Area

DMN1008UFDF
Datasheet number: DS38322 Rev. 4 - 2



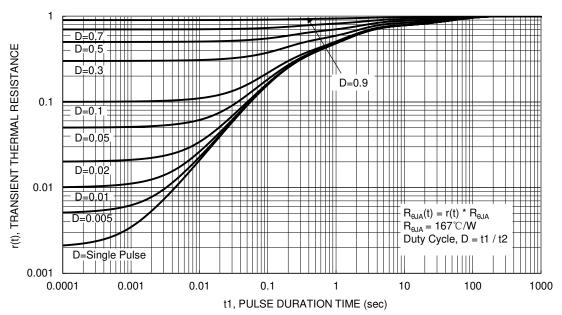


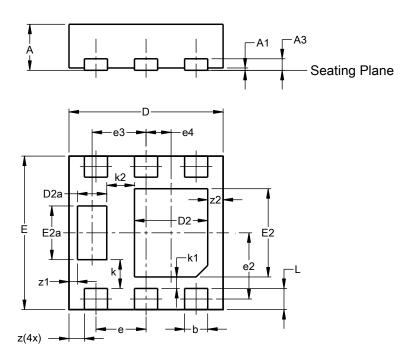
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

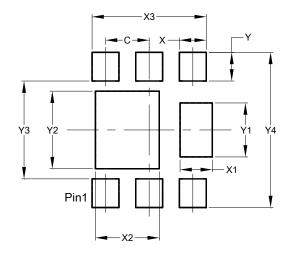


U-DFN2020-6						
		e F)				
Dim	Min	Max	Тур			
Α	0.57	0.63	0.60			
A 1	0.00	0.05	0.03			
A3	-	-	0.15			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	0.85	1.05	0.95			
D2a	0.33	0.43	0.38			
Е	1.95	2.05	2.00			
E2	1.05	1.25	1.15			
E2a	0.65	0.75	0.70			
е	(0.65 BS	С			
e2	C	.863 BS	SC			
e3	(0.70 BS	С			
e4	C	.325 BS	SC			
k	(0.37 BS	С			
k1	(0.15 BS	С			
k2		0.36 BS	С			
L	0.225	0.325	0.275			
Z	0.20 BSC					
z1	C).110 BS	SC			
z2		0.20 BS	С			
All C)imens	ions in	mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Υ	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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